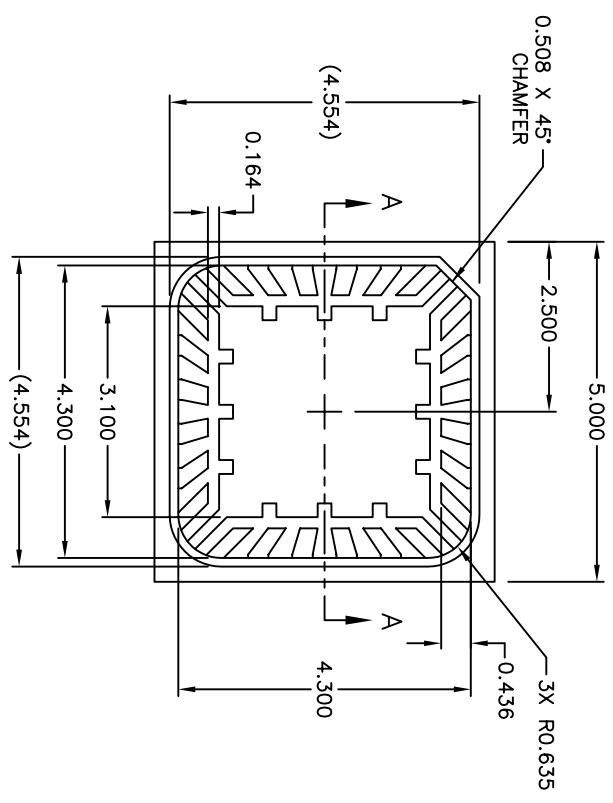


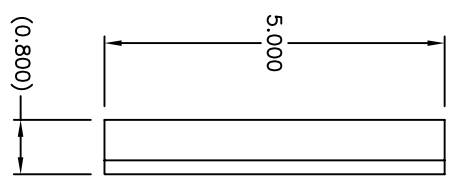
2

1

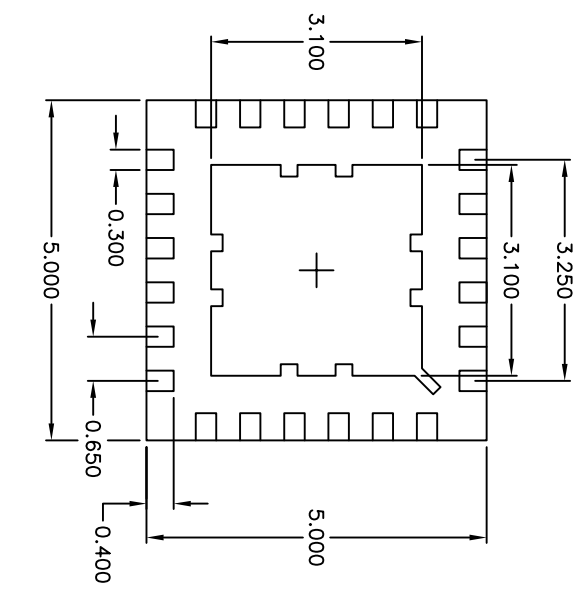
| REVISIONS | | | APPROVED |
|-----------|----------|--------------------|------------|
| ECON NO. | DATE | DESCRIPTION | |
| 10492 | 10/26/05 | PRODUCTION RELEASE | D.BENANDIO |



TOP VIEW



SECTION A-A



BOTTOM VIEW

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 3.100 X 3.100.
 6. JEDEC OUTLINE: MO-220 (VHHC-1).



THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS
 TOLERANCES ARE: X.XXX ± 0.015
 ANGLES: ± 1°
 DO NOT SCALE DRAWING

| | | | |
|----------|--------------|------|----------|
| DRAWN BY | W. GRIFFITTS | DATE | 10/26/05 |
| APP BY | P. FLASKERUD | DATE | 10/26/05 |
| CUSTOMER | --- | | |

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24 Lead 5mm x 5mm
 MLP Open-Pak

| | | |
|------|-----------------|-----|
| SIZE | PART NO. | REV |
| A | MLP5X5-24-OP-01 | 2 |

SCALE NONE

2

1